



WL18xxMOD WiLink™ 8 Single-Band Combo Module – Wi-Fi®, Bluetooth®, and Bluetooth Low Energy (BLE)

1 Device Overview

1.1 Features

- General
 - Single WLAN Module Integrates RF, Power Amps, Crystal, RF Switches, Filters, Passives, and Power Management
 - Direct Connect to Battery Using Integrated Switched-Mode Power Supplies (DC-DC)
 - Dual-Mode *Bluetooth* and BLE (WL183xMOD Only)
 - FCC, IC, ETSI/CE, and TELEC Certified with Chip Antenna
 - Hardware Design Guide and Files (COM8)
 - Host Controller Interface (HCI) Transport for *Bluetooth* Over UART and SDIO for WLAN
 - Temperature Compensation to Minimize Variation in RF Performance Over Entire Temperature Range
 - Operating Temperature: –20°C to 70°C
 - Small Form Factor: 13.3 × 13.4 × 2 mm
 - 100-Pin MOC Package
- Wi-Fi
 - WLAN Baseband Processor and RF Transceiver Support of IEEE Std 802.11a, 802.11b, 802.11g, and 802.11n
 - 2.4-GHz MRC Support for Extended Range
 - Fully Calibrated: Production Calibration Not Required
 - 4-Bit SDIO Host Interface Support
 - 20-MHz 2 × 2 MIMO and 20- or 40- MHz SISO Channels for High Throughput: 80 Mbps (TCP), 100 Mbps (UDP)
 - Wi-Fi Direct Concurrent Operation (Multichannel, Multirole)
 - SmartConfig™ Connects In-Home Devices to Wi-Fi in One Step
- *Bluetooth* and BLE (WL18xMOD Only)
 - *Bluetooth* 4.0 and CSA2 Support
 - Dedicated Audio Processor Support of SBC Encoding + A2DP
 - Royalty-Free Certified Stack From StoneStreet One
- Key Benefits
 - Reduces Design Overhead
 - 1.4X the Range Versus a Single Antenna
 - Differentiated Use-Cases by Configuring WiLink 8 Simultaneously in Two Roles (STA and AP) to Connect Directly with Other Wi-Fi Devices on Different RF Channel (Wi-Fi Networks)
 - SmartConfig Technology Connects In-Home Devices to Wi-Fi in One Step
 - Lowest Wi-Fi Power Consumption in Connected Idle (< 800 µA)
 - Configurable Wake on WLAN Filters to Only Wake Up the System
 - Wi-Fi-*Bluetooth* Single Antenna Coexistence
 - Available as Easy-to-Use FCC, ETSI, and Telec-Certified Module
 - Lower Manufacturing Costs Saves Board Space and Minimizes RF Expertise
 - AM335x Linux® and Android™ Reference Platform Accelerates Customer Development and Time to Market

1.2 Applications

- Internet of Things
- Multimedia
- Home Electronics
- Home Appliances and White Goods
- Industrial and Home Automation
- Smart Gateway and Metering
- Video Conferencing
- Video Camera and Security



1.3 Description

The precertified WiLink 8 module from TI offers high throughput and extended range along with Wi-Fi and *Bluetooth* coexistence (WL183x modules only) in a power-optimized design. Drivers for the Linux and Android high-level operating systems (HLOSs) are available free of charge from TI for the Sitara AM335x microprocessor (Linux and Android version restrictions apply).

Device Information

ORDER NUMBER	PACKAGE	BODY SIZE
WL1801MOD	MOC (100)	13.3 mm × 13.4 mm × 2 mm
WL1805MOD	MOC (100)	13.3 mm × 13.4 mm × 2 mm
WL1831MOD	MOC (100)	13.3 mm × 13.4 mm × 2 mm
WL1835MOD	MOC (100)	13.3 mm × 13.4 mm × 2 mm

1.4 Functional Block Diagram

Figure 1-1 shows a functional block diagram of the WL1835 variant.

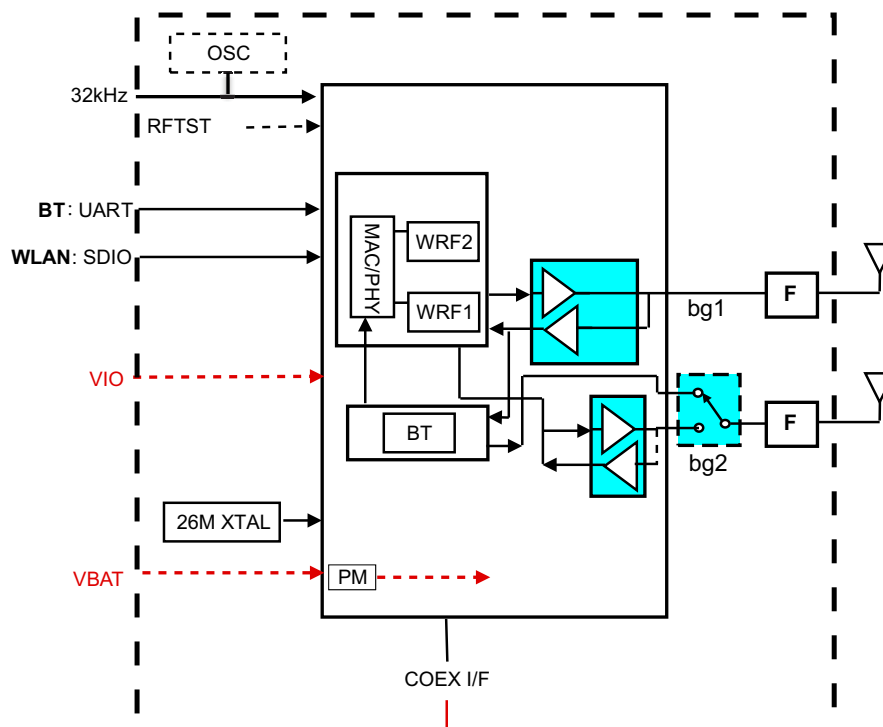


Figure 1-1. WL1835 Functional Block Diagram

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2 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision H (March 2014) to Revision I	Page
• Changed organizational flow of document in compliance with Data Sheet Council standard	1
• Changed functional block diagram	2
• Changed Pin Description table to organize by pin function and colors	7
• Deleted MCS32 MM 4K condition in <i>WLAN 2.4-GHz Receiver Characteristics</i>	12
• Deleted footnote 3 in Section 5.7.2 , <i>WLAN 2.4-GHz Transmitter Power</i>	13
• Deleted <i>Bluetooth</i> specification values in Section 5.8 , <i>Bluetooth Performance</i>	14
• Deleted <i>Slow Clock/RTC</i> and <i>Fast-Clock System</i> sections	18
• Added Section 5.12.5 , <i>Bluetooth-BLE Power-Up Sequence</i>	20
• Deleted information on throughput at variant ambient conditions in Section 7.1.5 , <i>Thermal Board Recommendations</i>	33

3 Device Comparison

The TI WiLink 8 module offers four footprint-compatible 2.4-GHz variants providing stand-alone and *Bluetooth* combo connectivity. [Table 3-1](#) compares the features of the module variants.

Table 3-1. TI WiLink 8 Module Variants

Device	WLAN 2.4-GHz SISO ⁽¹⁾	WLAN 2.4-GHz MIMO ⁽¹⁾	WLAN 2.4-GHz MRC ⁽¹⁾	<i>Bluetooth</i>
WL1835MOD	√	√	√	√
WL1831MOD	√			√
WL1805MOD	√	√	√	
WL1801MOD	√			

(1) SISO: single input, single output; MIMO: multiple input, multiple output; MRC: maximum ratio combining.

4 Terminal Configuration and Functions

Figure 4-1 shows the pin assignments for the 100-pin MOC package.

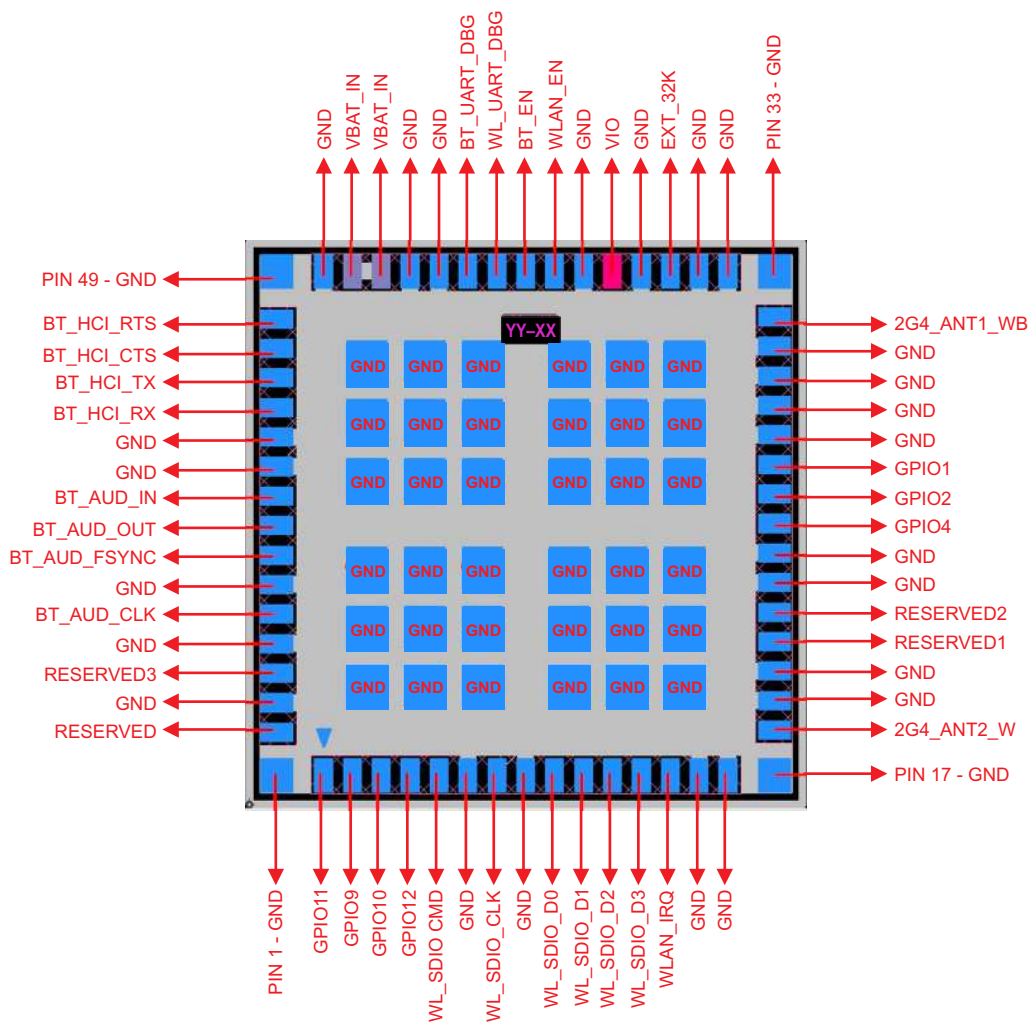
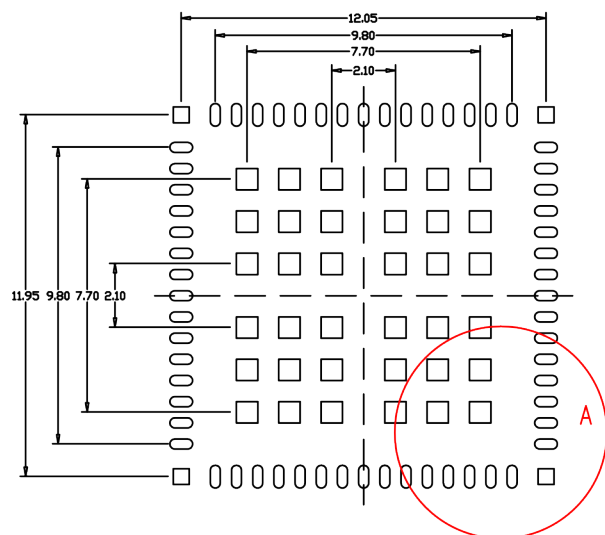


Figure 4-1. 100-Pin MOC Package (Bottom View)

Figure 4-2 shows the outline of the 100-pin MOC package.

Recommended Stencil:

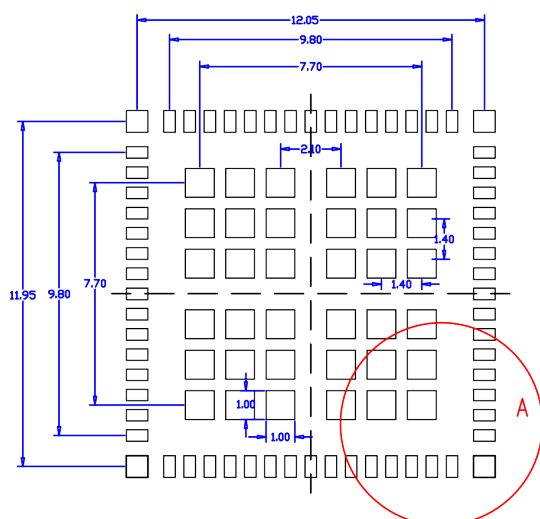


NOTE: 1. Module size: 13.4 x 13.3 mm
2. Pad size: 0.75 x 0.40 mm
3. Pitch: 0.7 mm

Figure 4-2. Outline of 100-Pin MOC Package (Bottom View)

Figure 4-3 shows the outline of the recommended PCB pattern for the 100-pin MOC package.

PCB Pattern Recommend:



Surround each pad with a 0.03mm wide solder mask

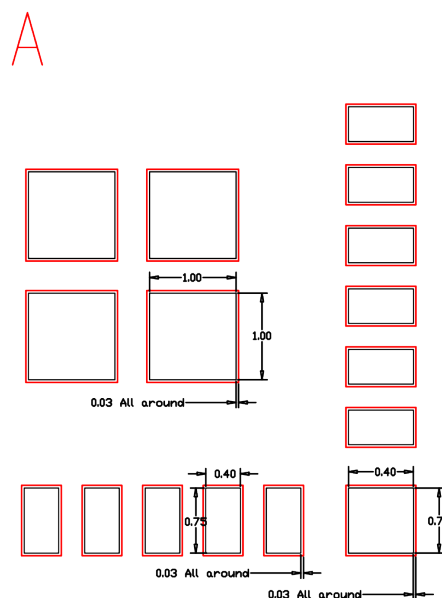


Figure 4-3. Outline of Recommended PCB Pattern for 100-Pin MOC Package (Bottom View)

4.1 Pin Description

Table 4-1 describes the module pins.

Table 4-1. Pin Description

Pin Name	Pin	Type/ Dir	Shutdown State	After Power Up ⁽¹⁾	Voltage Level	Connectivity ⁽²⁾				Description
						1801	1805	1831	1835	
Clocks and Reset Signals										
WL_SDIO_CLK_1V8	8	I	Hi-Z	Hi-Z	1.8 V	v	v	v	v	WLAN SDIO clock. Must be driven by the host.
EXT_32K	36	ANA			—	v	v	v	v	Input sleep clock: 32.768 kHz
WLAN_EN	40	I	PD	PD	1.8 V	v	v	v	v	Mode setting: high = enable
BT_EN	41	I	PD	PD	1.8 V	x	x	v	v	Mode setting: high = enable
Power-Management Signals										
VIO_IN	38	POW	PD	PD	1.8 V	v	v	v	v	Connect to 1.8-V external VIO
VBAT_IN	46	POW			VBAT	v	v	v	v	Power supply input, 2.9 to 4.8 V
VBAT_IN	47	POW			VBAT	v	v	v	v	Power supply input, 2.9 to 4.8 V
TI Reserved										
GPIO11	2	I/O	PD	PD	1.8 V	v	v	v	v	Reserved for future use. NC if not used.
GPIO9	3	I/O	PD	PD	1.8 V	v	v	v	v	Reserved for future use. NC if not used.
GPIO10	4	I/O	PU	PU	1.8 V	v	v	v	v	Reserved for future use. NC if not used.
GPIO12	5	I/O	PU	PU	1.8 V	v	v	v	v	Reserved for future use. NC if not used.
RESERVED1	21	I	PD	PD	1.8 V	x	x	x	x	Reserved for future use. NC if not used.
RESERVED2	22	I	PD	PD	1.8 V	x	x	x	x	Reserved for future use. NC if not used.
GPIO4	25	I/O	PD	PD	1.8 V	v	v	v	v	Reserved for future use. NC if not used.
RESERVED3	62	O	PD	PD	1.8 V	x	x	x	x	Reserved for future use. NC if not used.
WLAN Functional Block: Int Signals										
WL_SDIO_CMD_1V8	6	I/O	Hi-Z	Hi-Z	1.8 V	v	v	v	v	WLAN SDIO command in ⁽³⁾
WL_SDIO_D0_1V8	10	I/O	Hi-Z	Hi-Z	1.8 V	v	v	v	v	WLAN SDIO data bit 0 ⁽³⁾
WL_SDIO_D1_1V8	11	I/O	Hi-Z	Hi-Z	1.8 V	v	v	v	v	WLAN SDIO data bit 1 ⁽³⁾
WL_SDIO_D2_1V8	12	IO	Hi-Z	Hi-Z	1.8 V	v	v	v	v	WLAN SDIO data bit 2 ⁽³⁾

(1) PU = pullup; PD = pulldown.

(2) v = connect; x = no connect.

(3) Host must provide PU using a 10-K resistor for all non-CLK SDIO signals.

Table 4-1. Pin Description (continued)

Pin Name	Pin	Type/ Dir	Shutdown State	After Power Up ⁽¹⁾	Voltage Level	Connectivity ⁽²⁾				Description
						1801	1805	1831	1835	
WL_SDIO_D3_1V8	13	I/O	Hi-Z	PU	1.8 V	v	v	v	v	WLAN SDIO data bit 3. Changes state to PU at WL_EN or BT_EN assertion for card detects. Later disabled by software during initialization. (1)
WL_IRQ_1V8	14	O	PD	0	1.8 V	v	v	v	v	SDIO available, interrupt out. Active high. (For WL_RS232_TX/RX pullup is at power up.) Set to rising edge (active high) on power up. The Wi-Fi interrupt line can be configured by the driver according to the IRQ configuration (polarity/level/edge).
GPIO2	26	I/O	PD	PD	1.8 V	v	v	v	v	WL_RS232_RX (when WLAN_IRQ = 1 at power up)
2G4_ANT2_W	18	ANA			–	x	v	x	v	2.4G ant2 TX, RX
GPIO1	27	I/O	PD	PD	1.8 V	v	v	v	v	WL_RS232_TX (when WLAN_IRQ = 1 at power up)
2G4_ANT1_WB	32	ANA			–	v	v	v	v	2.4G ant1 TX, RX
WL_UART_DBG	42	O	PU	PU	1.8 V	v	v	v	v	Option: WLAN logger
Bluetooth Functional Block: Int Signals										
BT_UART_DBG	43	O	PU	PU	1.8 V	x	x	v	v	Option: <i>Bluetooth</i> logger
BT_HCI_RTS_1V8	50	O	PU	PU	1.8 V	x	x	v	v	UART RTS to host. NC if not used.
BT_HCI_CTS_1V8	51	I	PU	PU	1.8 V	x	x	v	v	UART CTS from host. NC if not used.
BT_HCI_TX_1V8	52	O	PU	PU	1.8 V	x	x	v	v	UART TX to host. NC if not used.
BT_HCI_RX_1V8	53	I	PU	PU	1.8 V	x	x	v	v	UART RX from host. NC if not used.
BT_AUD_IN	56	I	PD	PD	1.8 V	x	x	v	v	<i>Bluetooth</i> PCM/I2S bus. Data in. NC if not used.
BT_AUD_OUT	57	O	PD	PD	1.8 V	x	x	v	v	<i>Bluetooth</i> PCM/I2S bus. Data out. NC if not used.
BT_AUD_FSYNC	58	I/O	PD	PD	1.8 V	x	x	v	v	<i>Bluetooth</i> PCM/I2S bus. Frame sync. NC if not used.
BT_AUD_CLK	60	I/O	PD	PD	1.8 V	x	x	v	v	<i>Bluetooth</i> PCM/I2S bus. NC if not used.

Table 4-1. Pin Description (continued)

Pin Name	Pin	Type/ Dir	Shutdown State	After Power Up ⁽¹⁾	Voltage Level	Connectivity ⁽²⁾				Description
						1801	1805	1831	1835	
Ground Pins										
GND	1, 7, 9, 15, 16, 17, 19, 20, 23, 24, 28, 29, 30, 31, 33, 34, 35, 37, 39, 44, 45, 48, 49, 54, 55, 59, 61, 63, 64, G1-G36	GND			—	V	V	V	V	

5 Specifications

5.1 Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

Parameter	Value	Unit
VBAT	4.8 ⁽²⁾	V
VIO	–0.5 to 2.1	V
Input voltage to analog pins	–0.5 to 2.1	V
Input voltage limits (CLK_IN)	–0.5 to VDD_IO	V
Input voltage to all other pins	–0.5 to (VDD_IO + 0.5 V)	V
Operating ambient temperature range	–20 to +70 ⁽³⁾	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) 4.8 V cumulative to 2.33 years, including charging dips and peaks
- (3) Operating free-air temperature range at which the device can operate reliably for 15K cumulative active TX power-on hours (assuming a maximum junction temperature of (T_j) of 125°C). [Section 5.3, Power-On Hours \(POH\)](#), describes the correlation between T_j and PoH. In the WL18xx system, a control mechanism automatically ensures T_j < 125°C. Whenever T_j approaches the threshold, this mechanism controls the transmitter patterns.

5.2 Handling Ratings

		MIN	MAX	UNIT
T _{stg}	Storage temperature range	–40	+85	°C
ESD stress voltage ⁽¹⁾	Human body model (HBM) ⁽²⁾	–1000	+1000	V
	Charged device model (CDM) ⁽³⁾	–250	+250	

- (1) ESD measures device sensitivity and immunity to damage caused by electrostatic discharges into the device.
- (2) The level listed is the passing level per ANSI/ESDA/JEDEC JS-001. JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process, and manufacturing with less than 500-V HBM is possible, if necessary precautions are taken. Pins listed as 1000 V can actually have higher performance.
- (3) The level listed is the passing level per EIA-JEDEC JESD22-C101E. JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process, and manufacturing with less than 250-V CDM is possible, if necessary precautions are taken. Pins listed as 250 V can actually have higher performance.

5.3 Power-On Hours (POH)

Operating Junction Temperature (°C)	POH
125	15,000
120	20,000
115	27,000
110	37,000
105	50,000

5.4 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
VBAT ⁽¹⁾	DC supply range for all modes	2.9		4.8	V
	1.8-V I/O ring power supply voltage	1.62		1.95	V
V _{IH}	I/O high-level input voltage	0.65 × VDD_IO		VDD_IO	V
V _{IL}	I/O low-level input voltage	0		0.35 × VDD_IO	V
VIH_EN	Enable inputs high-level input voltage	1.365		VDD_IO	V

- (1) 4.8 V is applicable only for 2.3 years (30% of the time). Otherwise, maximum VBAT must not exceed 4.3 V.

Recommended Operating Conditions (continued)

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
VIL_EN	Enable inputs low-level input voltage		0		0.4	V
VOH	High-level output voltage	@ 4 mA	VDD_IO –0.45		VDD_IO	V
VOL	Low-level output voltage	@ 4 mA	0		0.45	V
Tr, Tf	Input transitions time Tr, Tf from 10% to 90% (digital I/O) ⁽²⁾		1		10	ns
Tr	Output rise time from 10% to 90% (digital pins) ⁽²⁾	CL < 25 pF			5.3	ns
Tf	Output fall time from 10% to 90% (digital pins) ⁽²⁾	CL < 25 pF			4.9	ns
	Ambient operating temperature		–20		70	°C
Maximum power dissipation	WLAN operation				2.8	W
	Bluetooth operation				0.2	

(2) Applies to all digital lines except SDIO, UART, I2C, PCM and slow clock lines

5.5 External Digital Slow Clock Requirements

The supported digital slow clock is 32.768 kHz digital (square wave). All core functions share a single input.

Parameter	Condition	Sym	Min	Typ	Max	Unit
Input slow clock frequency				32768		Hz
Input slow clock accuracy (Initial + temp + aging)	WLAN, Bluetooth				±250	ppm
Input transition time Tr, Tf (10% to 90%)		Tr, Tf			200	ns
Frequency input duty cycle			15	50	85	%
Input voltage limits	Square wave, DC-coupled	Vih	0.65 x VDD_IO		VDD_IO	Vpeak
		Vil	0		0.35 x VDD_IO	
Input impedance			1			MΩ
Input capacitance					5	pF

5.6 Thermal Characteristics

AIR FLOW		
NAME	DESCRIPTION	FCBGA (°C/W) ⁽¹⁾
θJC	Junction to case	12.7
θJB	Junction to board	13.6
θJA	Junction to free air ⁽²⁾	20.5
ΦJB	Junction to board	8.7

(1) °C/W = degrees Celsius per watt

(2) According to the JEDEC EIA/JESD 51 document

5.7 WLAN Performance

All RF and performance numbers are aligned to the module pin.

5.7.1 WLAN 2.4-GHz Receiver Characteristics

over operating free-air temperature range (unless otherwise noted)

Parameter	Condition	Min	Typ	Max	Unit
Operation frequency range	2400 to 2480	2400		2480	MHz
Sensitivity: 20-MHz bandwidth. At < 10% PER limit	1 Mbps DSSS		–96.3		dBm
	2 Mbps DSSS		–93.2		
	5.5 Mbps CCK		–90.6		
	11 Mbps CCK		–87.9		
	6 Mbps OFDM		–92.0		
	9 Mbps OFDM		–90.4		
	12 Mbps OFDM		–89.5		
	18 Mbps OFDM		–87.2		
	24 Mbps OFDM		–84.1		
	36 Mbps OFDM		–80.7		
	48 Mbps OFDM		–76.5		
	54 Mbps OFDM		–74.9		
	MCS0 MM 4K		–90.4		
	MCS1 MM 4K		–87.6		
	MCS2 MM 4K		–85.9		
	MCS3 MM 4K		–82.8		
	MCS4 MM 4K		–79.4		
	MCS5 MM 4K		–75.2		
	MCS6 MM 4K		–73.5		
	MCS7 MM 4K		–72.4		
	MCS0 MM 4K 40 MHz		–86.7		
	MCS7 MM 4K 40 MHz		–67.0		
	MCS0 MM 4K MRC		–92.7		
	MCS7 MM 4K MRC		–75.2		
	MCS13 MM 4K		–73.7		
	MCS14 MM 4K		–72.3		
	MCS15 MM 4K		–71.0		
Max Input Level At < 10% PER limit	OFDM (11g/n)	–19	–9		dBm
	DSSS	–4	–0		dBm
Adjacent channel rejection: Sensitivity level +3 dB for OFDM; Sensitivity level +6 dB for 11b	2 Mbps DSSS	42.7			dB
	11 Mbps CCK	37.9			dB
	54 Mbps OFDM	2.0			dB

5.7.2 WLAN 2.4-GHz Transmitter Power

over operating free-air temperature range (unless otherwise noted)

Parameter	Condition	RF_IO2_BG_WL pin 2.4-GHz SISO			Unit
		Min	Typ	Max	
Output Power: Maximum RMS output power measured at 1 dB from IEEE spectral mask or EVM ⁽¹⁾	1 Mbps DSSS		17.3		dBm
	2 Mbps DSSS		17.3		
	5.5 Mbps CCK		17.3		
	11 Mbps CCK		17.3		
	6 Mbps OFDM		17.1		
	9 Mbps OFDM		17.1		
	12 Mbps OFDM		17.1		
	18 Mbps OFDM		17.1		
	24 Mbps OFDM		16.2		
	36 Mbps OFDM		15.3		
	48 Mbps OFDM		14.6		
	54 Mbps OFDM		13.8		
	MCS0 MM		16.1		
	MCS1 MM		16.1		
	MCS2 MM		16.1		
	MCS3 MM		16.1		
	MCS4 MM		15.3		
	MCS5 MM		14.6		
	MCS6 MM		13.8		
	MCS7 MM ⁽²⁾		12.6		
	MCS0 MM 40 MHz		14.8		
	MCS7 MM 40 MHz		11.3		
	2G4_ANT2_W + 2G4_ANT1_WB 2.4-GHz MIMO				dBm
	MCS12 (WL18x5)		18.5		
	MCS13 (WL18x5)		17.4		
	MCS14 (WL18x5)		14.5		
	MCS15 (WL18x5)		13.4		
	2G4_ANT2_W + 2G4_ANT1_WB Pins				
Operation frequency range		2412		2484	MHz
Return loss			–10.0		dB
Reference input impedance			50.0		Ω

- (1) Regulatory constraints limit TI module output power to the following:
- Channels 1, 11, 13 @ OFDM legacy and HT 20-MHz rates: 14 dBm
 - Channels 1, 11, 13 @ HT 40-MHz lower rates: 12 dBm
 - Channel 7 @ HT 40-MHz lower rates: 12 dBm
 - Channel 5 @ HT 40-MHz upper rates: 12 dBm
- (2) To ensure compliance with the EVM conditions specified in the PHY chapter of IEEE Std 802.11™ – 2012:
- MCS7 20 MHz channel 12 output power is 2 dB lower than the typical value.
 - MCS7 20 MHz channel 8 output power is 1 dB lower than the typical value.

5.7.3 WLAN Currents

	Specifications Items	Typ (avg) – 25°C	Units
Receiver	Low-power mode (LPM) 2.4-GHz RX SISO20 single chain	49	mA
	2.4 GHz RX search SISO20	54	mA
	2.4-GHz RX search MIMO20	74	mA
	2.4-GHz RX search SISO40	59	mA
	2.4-GHz RX 20 M SISO 11 CCK	56	mA
	2.4-GHz RX 20 M SISO 6 OFDM	61	mA
	2.4-GHz RX 20 M SISO MCS7	65	mA
	2.4-GHz RX 20 M MRC 1 DSSS	74	mA
	2.4-GHz RX 20 M MRC 6 OFDM	81	mA
	2.4-GHz RX 20 M MRC 54 OFDM	85	mA
	2.4-GHz RX 40 MHz MCS7	77	mA
Transmitter	2.4-GHz TX 20 M SISO 6 OFDM 15.4 dBm	285	mA
	2.4-GHz TX 20 M SISO 11 CCK 15.4 dBm	273	mA
	2.4-GHz TX 20 M SISO 54 OFDM 12.7 dBm	247	mA
	2.4-GHz TX 20 M SISO MCS7 11.2 dBm	238	mA
	2.4-GHz TX 20 M MIMO MCS15 11.2 dBm	420	mA
	2.4-GHz TX 40 M SISO MCS7 8.2 dBm	243	mA

5.8 Bluetooth Performance

All RF and performance numbers are aligned to the module pin.

5.8.1 Bluetooth BR, EDR Receiver Characteristics—In-Band Signals

over operating free-air temperature range (unless otherwise noted)

Parameter	Condition	Min	Typ	Max	Unit
Bluetooth BR, EDR operation frequency range		2402		2480	MHz
Bluetooth BR, EDR channel spacing			1		MHz
Bluetooth BR, EDR input impedance			50		Ω
Bluetooth BR, EDR sensitivity ⁽¹⁾ dirty TX on	BR, BER = 0.1%		–92.2		dBm
	EDR2, BER = 0.01%		–91.7		dBm
	EDR3, BER = 0.01%		–84.7		dBm
Bluetooth EDR BER floor at sensitivity + 10 dB Dirty TX off (for 1,600,000 bits)	EDR2	1e-6			
	EDR3	1e-6			
Bluetooth BR, EDR maximum usable input power	BR, BER = 0.1%	–5.0			dBm
	EDR2, BER = 0.1%	–15.0			dBm
	EDR3, BER = 0.1%	–15.0			dBm
Bluetooth BR intermodulation	Level of interferers for n = 3, 4, and 5	–36.0	–30.0		dBm

(1) Sensitivity degradation up to –3 dB may occur due to fast clock harmonics with dirty TX on.

Parameter	Condition		Min	Typ	Max	Unit
Bluetooth BR, EDR C/I performance Numbers show wanted signal-to-interfering-signal ratio. Smaller numbers indicate better C/I performances (Image frequency = −1 MHz)	BR, co-channel				10	dB
	EDR, co-channel	EDR2			12	dB
		EDR3			20	dB
	BR, adjacent ±1 MHz				−3.0	dB
	EDR, adjacent ±1 MHz, (image)	EDR2			−3.0	dB
		EDR3			2.0	dB
	BR, adjacent +2 MHz				−33.0	dB
	EDR, adjacent +2 MHz	EDR2			−33.0	dB
		EDR3			−28.0	dB
	BR, adjacent −2 MHz				−20.0	dB
	EDR, adjacent −2 MHz	EDR2			−20.0	dB
		EDR3			−13.0	dB
BR, adjacent ≥±31 MHz				−42.0	dB	
EDR, adjacent ≥±31 MHz	EDR2			−42.0	dB	
	EDR3			−36.0	dB	
Bluetooth BR, EDR RF return loss				−10.0		dB

5.8.2 Bluetooth Transmitter, BR

over operating free-air temperature range (unless otherwise noted)

Parameter	Min	Typ	Max	Unit
BR RF output power ⁽¹⁾	V _{BAT} $\geq$ 3 V	12.7		dBm
	V _{BAT} < 3 V	7.2		dBm
BR gain control range		30.0		dB
BR power control step		5.0		dB
BR adjacent channel power M–N = 2		–43.0		dBm
BR adjacent channel power M–N > 2		–48.0		dBm

(1) Values reflect maximum power. Reduced power is available using a vendor-specific (VS) command.

5.8.3 Bluetooth Transmitter, EDR

over operating free-air temperature range (unless otherwise noted)

Parameter	Min	Typ	Max	Unit
EDR output power ⁽¹⁾	V _{bat} $\geq$ 3 V	7.2		dBm
	V _{bat} < 3 V	5.2		
EDR relative power				dB
EDR gain control range		30		dB
EDR power control step		5		dB
EDR adjacent channel power M–N = 1		–36		dBc
EDR adjacent channel power M–N = 2		–30		dBm
EDR adjacent channel power M–N > 2		–42		dBm

(1) Values reflect default maximum power. Max power can be changed using a VS command.

5.8.4 Bluetooth Modulation, BR

over operating free-air temperature range (unless otherwise noted)

Characteristics	Condition ⁽¹⁾		Min	Typ	Max	Units
BR –20 dB bandwidth				925	995	kHz
BR modulation characteristics	Δf_{1avg}	Mod data = 4 1s, 4 0s: 111100001111...	145	160	170	kHz
	$\Delta f_{2max} \geq$ limit for at least 99.9% of all Δf_{2max}	Mod data = 1010101...	120	130		kHz
	$\Delta f_{2avg}/\Delta f_{1avg}$		85	88		%
BR carrier frequency drift	One slot packet		–25		25	kHz
	Three and five slot packet		–35		35	kHz
BR drift rate	$ f_{k+5} - f_k $, $k = 0 \dots \text{max}$				15	kHz/50 μ s
BR initial carrier frequency tolerance ⁽²⁾	$f_0 - f_{TX}$		± 75		± 75	kHz

(1) Performance values reflect maximum power.

(2) Numbers include XTAL frequency drift over temperature and aging.

5.8.5 Bluetooth Modulation, EDR

over operating free-air temperature range (unless otherwise noted)

Parameter ⁽¹⁾	Condition	Min	Typ	Max	Unit
EDR carrier frequency stability		–5		5	kHz
EDR initial carrier frequency tolerance ⁽²⁾		± 75		± 75	kHz
EDR RMS DEVM	EDR2		4	15	%
	EDR3		4	10	%
EDR 99% DEVM	EDR2			30	%
	EDR3			20	%
EDR peak DEVM	EDR2		9	25	%
	EDR3		9	18	%

(1) Performance values reflect maximum power.

(2) Numbers include XTAL frequency drift over temperature and aging.

5.9 Bluetooth LE Performance

All RF and performance numbers are aligned to the module pin.

5.9.1 Bluetooth LE Receiver Characteristics – In-Band Signals

over operating free-air temperature range (unless otherwise noted)

Parameter	Condition ⁽¹⁾	Min	Typ	Max	Unit
Bluetooth LE operation frequency range		2402		2480	MHz
Bluetooth LE channel spacing			2		MHz
Bluetooth LE input impedance			50		Ω
Bluetooth LE sensitivity ⁽²⁾ Dirty TX on			–92.2		dBm
Bluetooth LE maximum usable input power		–5			dBm
Bluetooth LE intermodulation characteristics	Level of interferers. For $n = 3, 4, 5$	–36	–30		dBm

(1) BER of 0.1% corresponds to PER of 30.8% for a minimum of 1500 transmitted packets, according to the Bluetooth LE test specification.

(2) Sensitivity degradation of up to –3 dB can occur due to fast clock harmonics.

Parameter	Condition ⁽¹⁾	Min	Typ	Max	Unit
Bluetooth LE C/I performance. Note: Numbers show wanted signal-to-interfering-signal ratio. Smaller numbers indicate better C/I performance.	LE, co-channel			12	dB
	LE, adjacent ± 1 MHz			0	
	LE, adjacent +2 MHz			-38	
	LE, adjacent -2 MHz			-15	
Image = -1 MHz	LE, adjacent $\geq \pm 3 $ MHz			-40	

5.9.2 Bluetooth LE Transmitter Characteristics

over operating free-air temperature range (unless otherwise noted)

Parameter		Min	Typ	Max	Unit
Bluetooth LE RF output power ⁽¹⁾	V _{BAT} $\geq$ 3 V		10.0		dBm
	V _{BAT} < 3 V		7.2		dBm
Bluetooth LE adjacent channel power M-N = 2			-51.0		dBm
Bluetooth LE adjacent channel power M-N > 2			-54.0		dBm

(1) To reduce the maximum BLE power, use a VS command. The optional extra margin is offered to compensate for design losses, such as trace and filter losses, and to achieve the maximum allowed output power at system level.

5.9.3 Bluetooth LE Modulation Characteristics

over operating free-air temperature range (unless otherwise noted)

Characteristics	Condition ⁽¹⁾		Min	Typ	Max	Units
Bluetooth LE modulation characteristics	Δf_{1avg}	Mod data = 4 1s, 4 0s: 111100001111...	240	250	260	kHz
	$\Delta f_{2max} \geq$ limit for at least 99.9% of all Δf_{2max}	Mod data = 1010101...	195	215		kHz
	$\Delta f_{2avg}/\Delta f_{1avg}$		85	90		%
Bluetooth LE carrier frequency drift	If ₀ – f _{nl} , n = 2,3 K		-25		25	kHz
Bluetooth LE drift rate	If ₁ – f _{0l} and If _n – f _{n-5l} , n = 6,7 K				15	kHz/50 μ s
LE initial carrier frequency tolerance ⁽²⁾	f _n – f _{TX}		± 75		± 75	kHz

(1) Performance values reflect maximum power.

(2) Numbers include XTAL frequency drift over temperature and aging.

5.10 Bluetooth-BLE Dynamic Currents

Current is measured at output power as follows:

- BR at 12.7 dBm
- EDR at 7.2 dBm

Use Case ^{(1) (2)}	Typ	Units
BR voice HV3 + sniff	11.6	mA
EDR voice 2-EV3 no retransmission + sniff	5.9	mA
Sniff 1 attempt 1.28 s	178.0	μ A
EDR A2DP EDR2 (master). SBC high quality – 345 Kbs	10.4	mA
EDR A2DP EDR2 (master). MP3 high quality – 192 Kbs	7.5	mA
Full throughput ACL RX: RX-2DH5 ⁽³⁾⁽⁴⁾	18.0	mA
Full throughput BR ACL TX: TX-DH5 ⁽⁴⁾	50.0	mA
Full throughput EDR ACL TX: TX-2DH5 ⁽⁴⁾	33.0	mA

(1) The role of Bluetooth in all scenarios except A2DP is slave.

(2) CL1P5 PA is connected to V_{BAT}, 3.7 V.

(3) ACL RX has the same current in all modulations.

(4) Full throughput assumes data transfer in one direction.

Use Case ^{(1) (2)}	Typ	Units
Page scan or inquiry scan (scan interval is 1.28 s or 11.25 ms, respectively)	253.0	μA
Page scan and inquiry scan (scan interval is 1.28 s and 2.56 s, respectively)	332.0	μA

5.11 Bluetooth LE Currents

All current measured at output power of 7.2 dBm

Use Case ⁽¹⁾	Typ	Units
Advertising, not connectable ⁽²⁾	131	μA
Advertising, discoverable ⁽²⁾	143	μA
Scanning ⁽³⁾	266	μA
Connected, master role, 1.28-s connect interval ⁽⁴⁾	124	μA
Connected, slave role, 1.28-s connect interval ⁽⁴⁾	132	μA

(1) CL1p% PA is connected to VBAT, 3.7 V.

(2) Advertising in all three channels, 1.28-s advertising interval, 15 bytes advertise data

(3) Listening to a single frequency per window, 1.28-s scan interval, 11.25-ms scan window

(4) Zero slave connection latency, empty TX and RX LL packets

5.12 Timing and Switching Characteristics

5.12.1 Power Management

5.12.1.1 Block Diagram – Internal DC2DCs

The device incorporates three internal DC2DCs (switched-mode power supplies) to provide efficient internal supplies, derived from V_{BAT}.

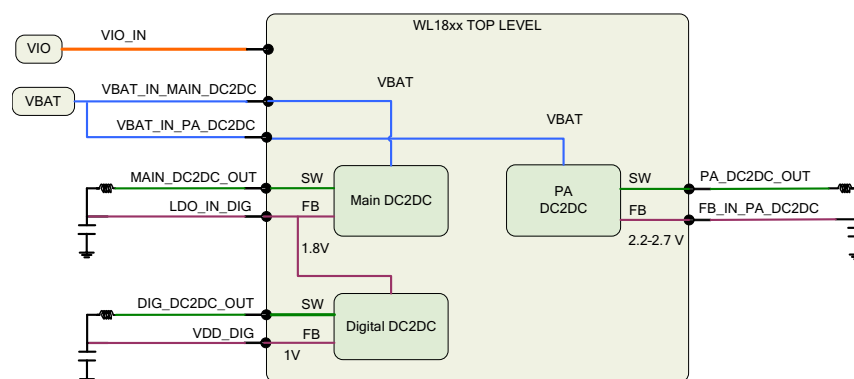


Figure 5-1. Internal DC2DCs

5.12.2 Power-Up and Shut-Down States

The correct power-up and shut-down sequences must be followed to avoid damage to the device.

While V_{BAT} or V_{IO} or both are deasserted, no signals should be driven to the device. The only exception is the slow clock that is a fail-safe I/O.

While V_{BAT}, V_{IO}, and slow clock are fed to the device, but WL_EN is deasserted (low), the device is in SHUTDOWN state. In SHUTDOWN state all functional blocks, internal DC2DCs, clocks, and LDOs are disabled.

To perform the correct power-up sequence, assert (high) WL_EN. The internal DC2DCs, LDOs, and clock start to ramp and stabilize. Stable slow clock, V_{IO}, and V_{BAT} are prerequisites to the assertion of one of the enable signals.

To perform the correct shut-down sequence, deassert (low) WL_EN while all the supplies to the device (V_{BAT} , V_{IO} , and slow clock) are still stable and available. The supplies to the chip (V_{BAT} and V_{IO}) can be deasserted only after both enable signals are deasserted (low).

Figure 5-2 shows the general power scheme for the module, including the powerdown sequence.

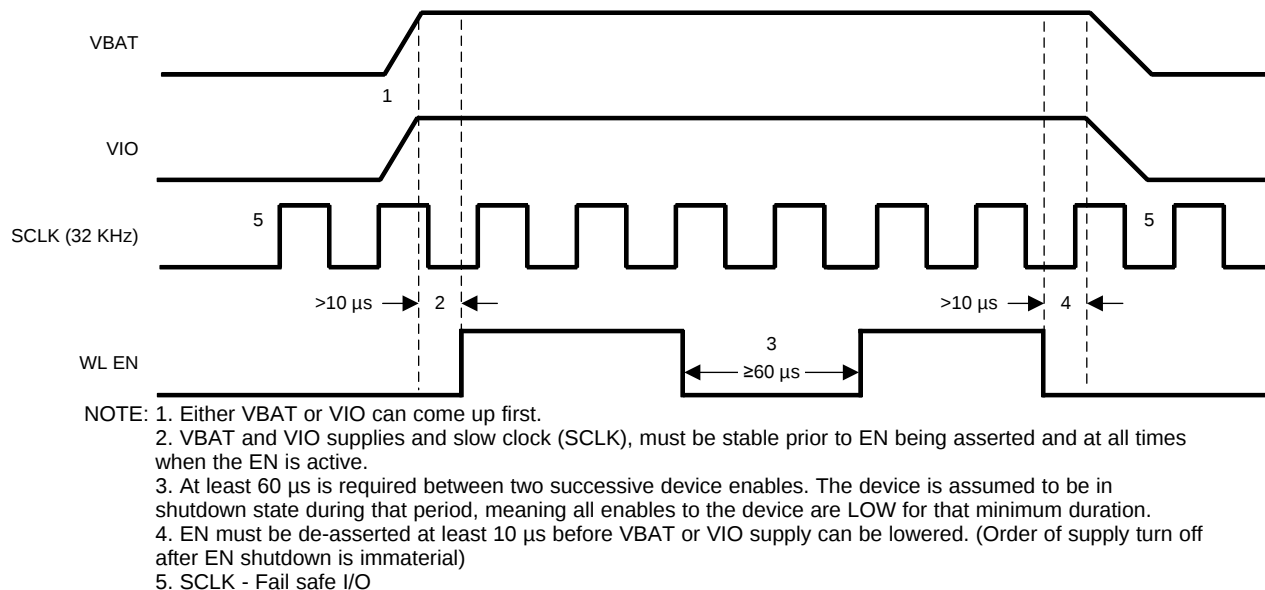


Figure 5-2. Power-Up System

5.12.3 Chip Top-level Power-Up Sequence

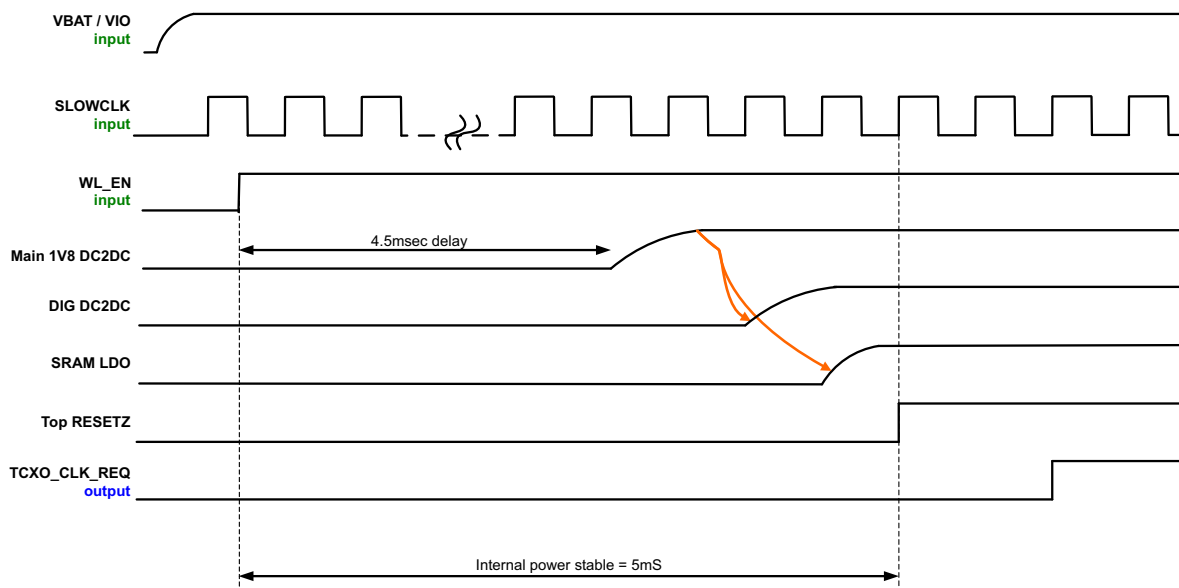


Figure 5-3. Chip Top-Level Power-Up Sequence

5.12.4 WLAN Power-Up Sequence

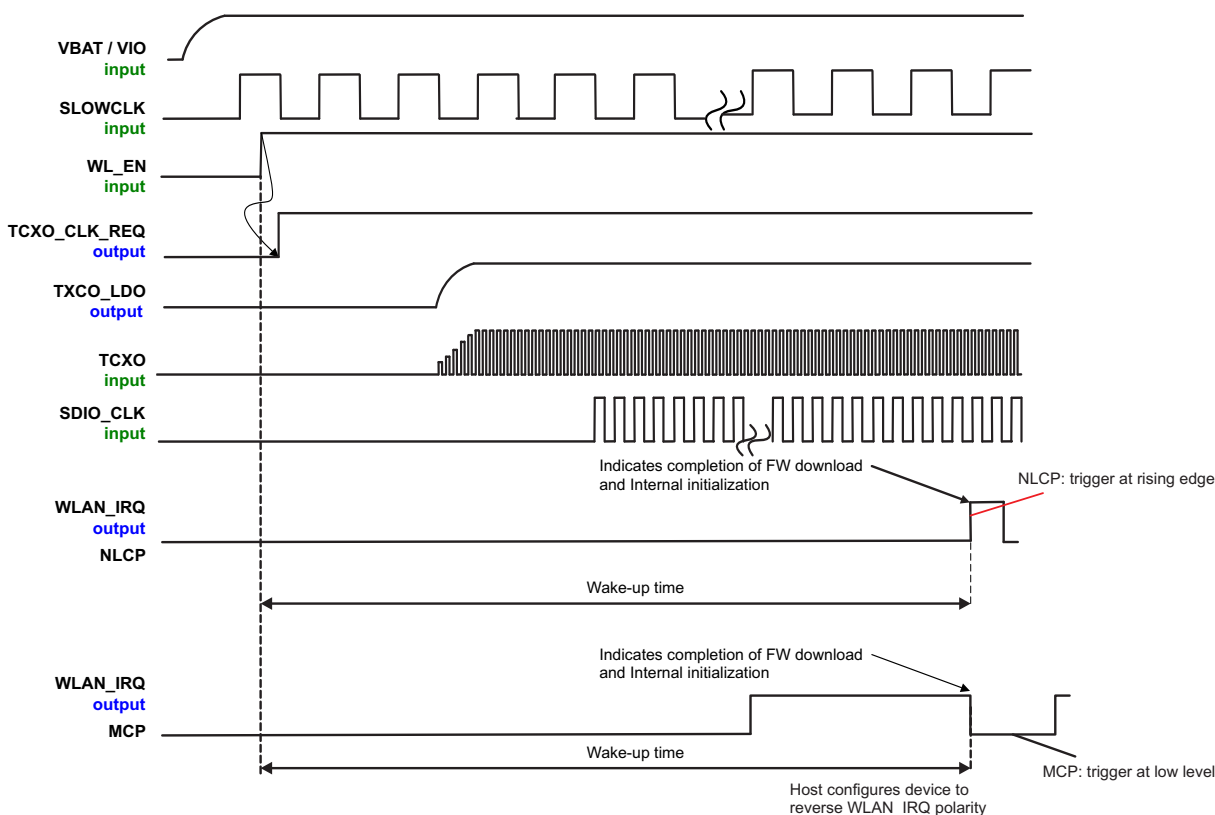


Figure 5-4. WLAN Power-Up Sequence

5.12.5 Bluetooth-BLE Power-Up Sequence

Figure 5-5 shows the Bluetooth-BLE power-up sequence.

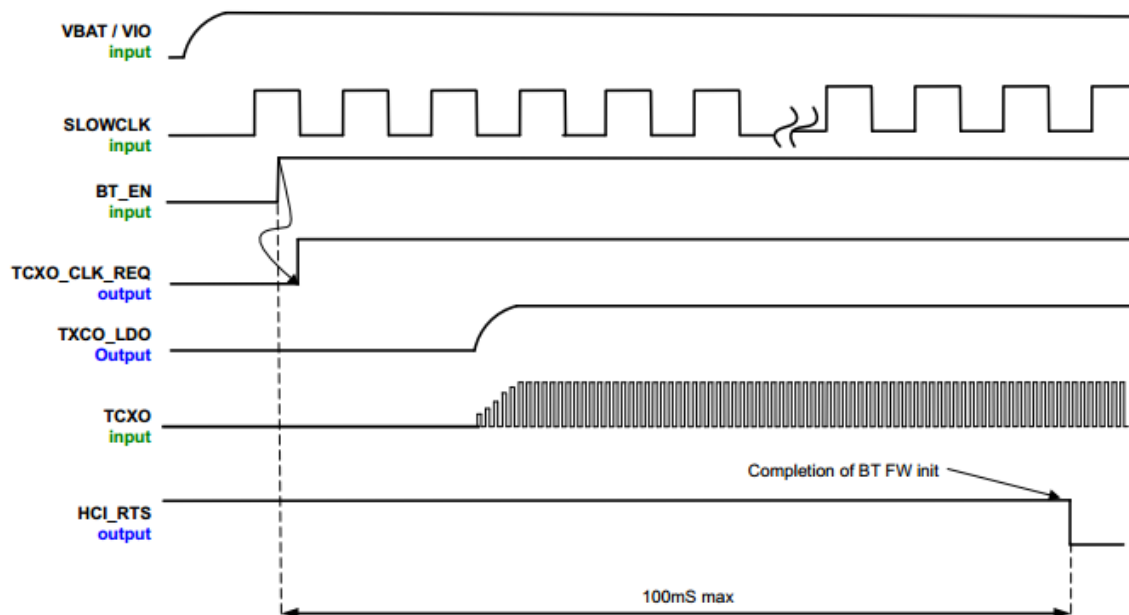


Figure 5-5. Bluetooth/BLE Power-Up Sequence

5.12.6 WLAN SDIO Transport Layer

The SDIO is the host interface for WLAN. The interface between the host and the WL18xx module uses an SDIO interface and supports a maximum clock rate of 50 MHz.

The device SDIO also supports the following features of the SDIO V3 specification:

- 4-bit data bus
- Synchronous and asynchronous in-band interrupt
- Default and high-speed (HS, 50 MHz) timing
- Sleep and wake commands

5.12.6.1 SDIO Timing Specifications

Figure 5-6 and Figure 5-7 show the SDIO switching characteristics over recommended operating conditions and with the default rate for input and output.

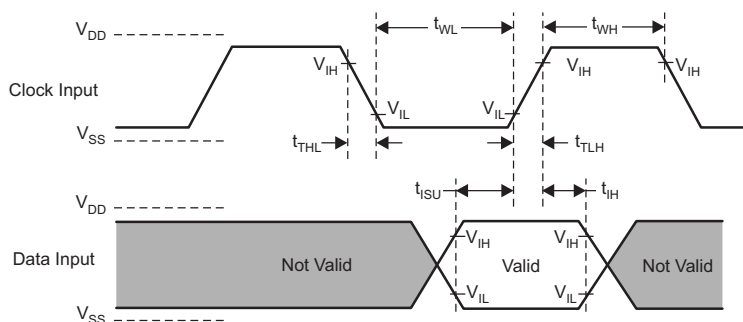


Figure 5-6. SDIO Default Input Timing

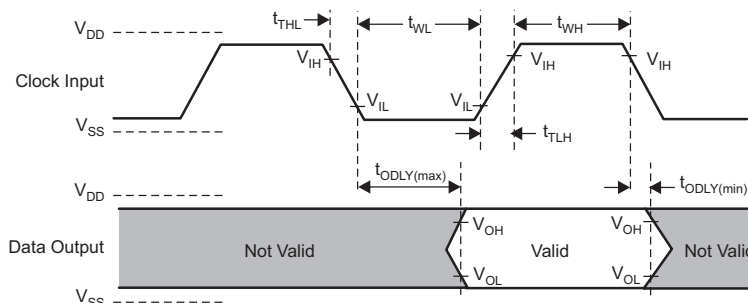


Figure 5-7. SDIO Default Output Timing

Table 5-1 lists the SDIO default timing characteristics.

Table 5-1. SDIO Default Timing Characteristics⁽¹⁾

Parameter ⁽²⁾		Min	Max	Unit
f_{clock}	Clock frequency, CLK	0.0	26.0	MHz
DC	Low, high duty cycle	40.0	60.0	%
t_{TLH}	Rise time, CLK		10.0	ns
t_{THL}	Fall time, CLK		10.0	ns
t_{ISU}	Setup time, input valid before CLK $\uparrow$	3.0		ns
t_{IH}	Hold time, input valid after CLK $\uparrow$	2.0		ns
t_{ODLY}	Delay time, CLK $\downarrow$ to output valid	7.0	10.0	ns
C_{I}	Capacitive load on outputs		15.0	pF

(1) To change the data out clock edge from the falling edge (default) to the rising edge, set the configuration bit.

(2) Parameter values reflect maximum clock frequency.

5.12.6.2 SDIO Switching Characteristics – High Rate

Figure 5-8 and Figure 5-9 show the parameters for maximum clock frequency.

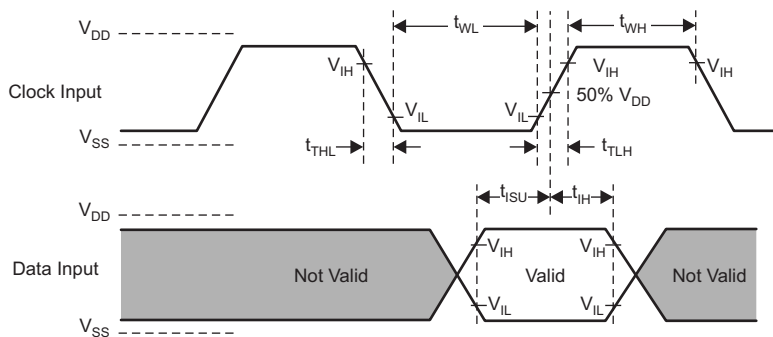


Figure 5-8. SDIO HS Input Timing

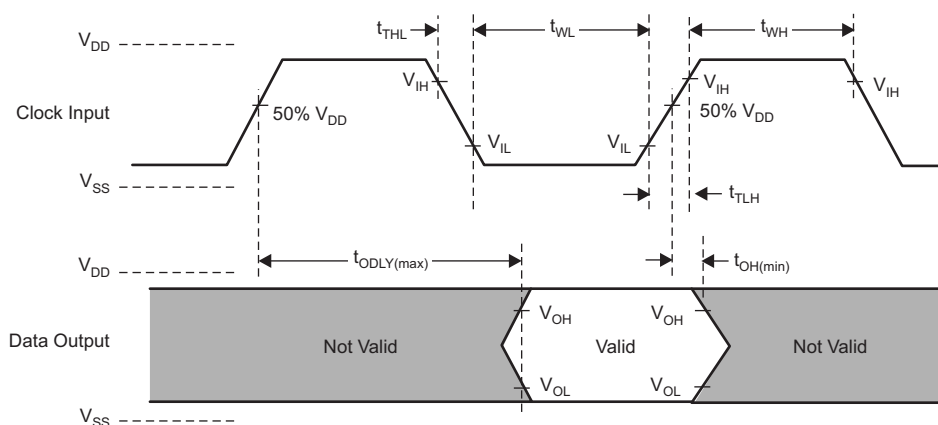


Figure 5-9. SDIO HS Output Timing

Table 5-2 lists the SDIO high-rate timing characteristics.

Table 5-2. SDIO HS Timing Characteristics

Parameter		Min	Max	Unit
f_{clock}	Clock frequency, CLK	0.0	52.0	MHz
DC	Low, high duty cycle	40.0	60.0	%
t_{TLH}	Rise time, CLK		3.0	ns
t_{THL}	Fall time, CLK		3.0	ns
t_{ISU}	Setup time, input valid before CLK $\uparrow$	3.0		ns
t_{IH}	Hold time, input valid after CLK $\uparrow$	2.0		ns
t_{ODLY}	Delay time, CLK $\uparrow$ to output valid	7.0	10.0	ns
C_{I}	Capacitive load on outputs		10.0	pF

5.12.7 HCI UART Shared Transport Layers for All Functional Blocks (Except WLAN)

The device incorporates a UART module dedicated to the *Bluetooth* shared-transport, host controller interface (HCI) transport layer. The HCI interface transports commands, events, and ACL between the *Bluetooth* device and its host using HCI data packets acting as a shared transport for all functional blocks except WLAN.

WLAN	Shared HCI for All Functional Blocks Except WLAN	Bluetooth Voice-Audio
WLAN HS SDIO	Over UART	Bluetooth PCM

The HCI UART supports most baud rates (including all PC rates) for all fast-clock frequencies up to a maximum of 4 Mbps. After power up, the baud rate is set for 115.2 kbps, regardless of the fast-clock frequency. The baud rate can then be changed using a VS command. The device responds with a Command Complete Event (still at 115.2 kbps), after which the baud rate change occurs.

HCI hardware includes the following features:

- Receiver detection of break, idle, framing, FIFO overflow, and parity error conditions
- Receiver-transmitter underflow detection
- CTS, RTS hardware flow control
- 4 wire (H4)

Table 5-3 lists the UART default settings.

Table 5-3. UART Default Setting

Parameter	Value
Bit rate	115.2 kbps
Data length	8 bits
Stop bit	1
Parity	None

5.12.7.1 UART 4-Wire Interface – H4

The interface includes four signals:

- TXD
- RXD
- CTS
- RTS

Flow control between the host and the device is byte-wise by hardware.

When the UART RX buffer of the device passes the flow-control threshold, the buffer sets the UART_RTS signal high to stop transmission from the host. When the UART_CTS signal is set high, the device stops transmitting on the interface. If HCI_CTS is set high in the middle of transmitting a byte, the device finishes transmitting the byte and stops the transmission.

Figure 5-10 shows the UART timing.

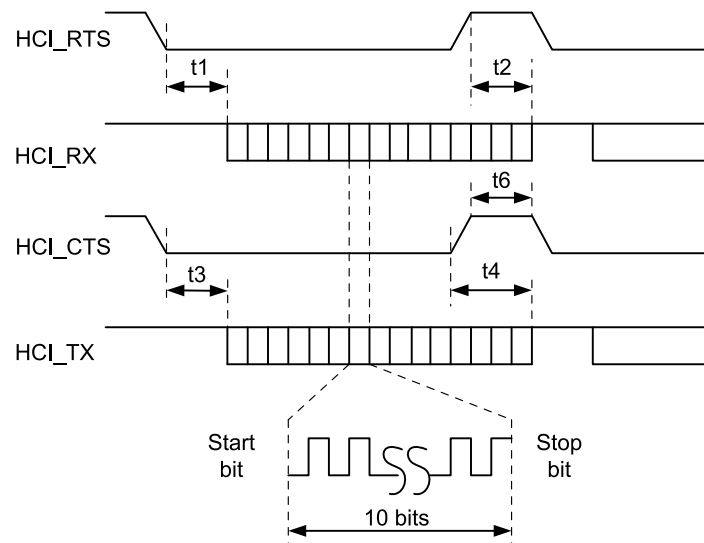


Figure 5-10. UART Timing Diagram

Table 5-4 lists the UART timing characteristics.

Table 5-4. UART Timing Characteristics

Parameter	Condition	Symbol	Min	Typ	Max	Unit
Baud rate			37.5		4364	Kbps
Baud rate accuracy per byte	Receive-transmit		–2.5		+1.5	%
Baud rate accuracy per bit	Receive-transmit		–12.5		+12.5	%
CTS low to TX_DATA on		t3	0.0	2.0		μs
CTS high to TX_DATA off	Hardware flow control	t4			1.0	Byte
CTS high pulse width		t6	1.0			Bit
RTS low to RX_DATA on		t1	0.0	2.0		μs
RTS high to RX_DATA off	Interrupt set to 1/4 FIFO	t2			16.0	Bytes

Figure 5-11 shows the UART data frame.

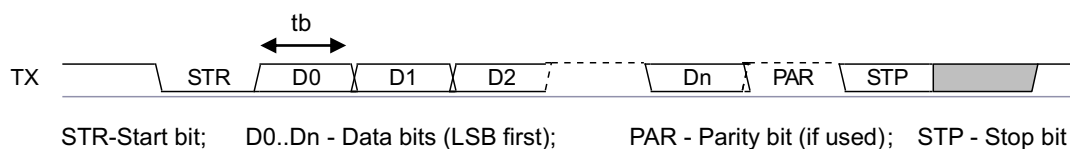


Figure 5-11. UART Data Frame

5.12.8 Bluetooth Codec-PCM (Audio) Timing Specifications

Figure 5-12 shows the Bluetooth codec-PCM (audio) timing diagram.

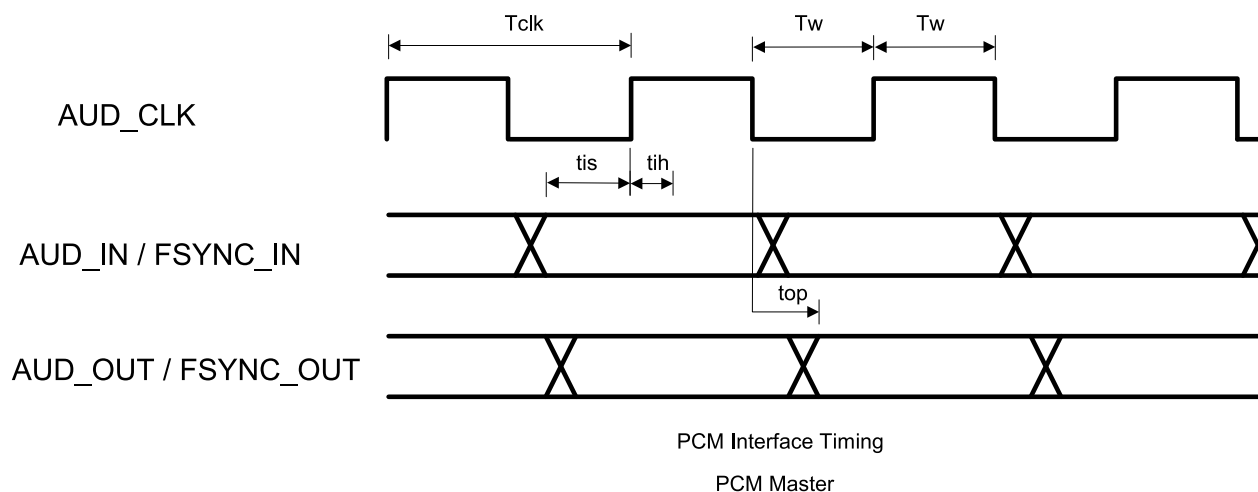


Figure 5-12. Bluetooth Codec-PCM (Audio) Master Timing Diagram

Table 5-5 lists the *Bluetooth* codec-PCM master timing characteristics.

Table 5-5. *Bluetooth* Codec-PCM Master Timing Characteristics

Parameter	Symbol	Min	Max	Unit
Cycle time	T_{clk}	162.76 (6.144 MHz)	15625 (64 kHz)	ns
High or low pulse width	T_s	35% of T_{clk} min		
AUD_IN setup time	t_{is}	10.6		
AUD_IN hold time	t_{ih}	0		
AUD_OUT propagation time	t_{op}	0	15	
FSYNC_OUT propagation time	t_{op}	0	15	
Capacitive loading on outputs	C_l		40	pF

Table 5-6 lists the *Bluetooth* codec-PCM slave timing characteristics.

Table 5-6. *Bluetooth* Codec-PCM Slave Timing Characteristics

Parameter	Symbol	Min	Max	Unit
Cycle time	T_{clk}	81.38 (12.266 MHz)		ns
High or low pulse width	T_w	35% of T_{clk} min		
AUD_IN setup time	t_{is}	5		
AUD_IN hold time	t_{ih}	0		
AUD_FSYNC setup time	t_{is}	5		
AUD_FSYNC hold time	t_{ih}	0		
AUD_OUT propagation time	t_{op}	0	19	
Capacitive loading on outputs	C_l		40	pF

6 Detailed Description

The WiLink 8 module is a self-contained connectivity solution based on WiLink 8 connectivity. As the eighth-generation connectivity combo chip from TI, the WiLink 8 module is based on proven technology.

Table 6-1 through Table 6-3 list performance parameters along with shutdown and sleep currents.

Table 6-1. WLAN Performance Parameters

WLAN ⁽¹⁾	Specification (Typ)	Conditions
Maximum TX power	17.3 dBm	1 Mbps DSSS
Minimum sensitivity	–96.3 dBm	1 Mbps DSSS
Sleep current	160 μ A	Leakage, firmware retained
Connected IDLE	750 μ A	No traffic IDLE connect
RX search	54 mA	Search (SISO20)
RX current (SISO20)	65 mA	MCS7, 2.4 GHz
TX current (SISO20) ⁽²⁾	238 mA	MCS7, 2.4 GHz, +11.2 dBm
Maximum peak current consumption during calibration ⁽³⁾	850 mA	

(1) System design power scheme must comply with both peak and average TX bursts.

(2) WLAN maximum VBAT current draw of 725 mA with MIMO continues burst configuration.

(3) Peak current VBAT can hit 850 mA during device calibration.

- At wakeup, the WiLink 8 module performs the entire calibration sequence at the center of the 2.4-GHz band.
- Once a link is established, calibration is performed periodically (every 5 minutes) on the specific channel tuned.
- The maximum VBAT value is based on peak calibration consumption with a 30% margin.

Table 6-2. Bluetooth Performance Parameters

Bluetooth	Specification (Typ)	Conditions
Maximum TX power	12.7 dBm	GFSK
Minimum sensitivity	–92.2 dBm	GFSK
Sniff	178 μ A	1 attempt, 1.28 s (+4 dBm)
Page or inquiry	253 μ A	1.28-s interrupt, 11.25-ms scan window (+4 dBm)
A2DP	7.5 mA	MP3 high quality 192 kbps (+4 dBm)

Table 6-3. Shutdown and Sleep Currents

Parameter	Power Supply Current	Typ	Unit
Shutdown mode All functions shut down	VBAT	10	μ A
	VIO	2	μ A
WLAN sleep mode	VBAT	160	μ A
Bluetooth sleep mode	VBAT	110	μ A

Figure 6-1 shows a high-level view of the WL1835MOD variant.

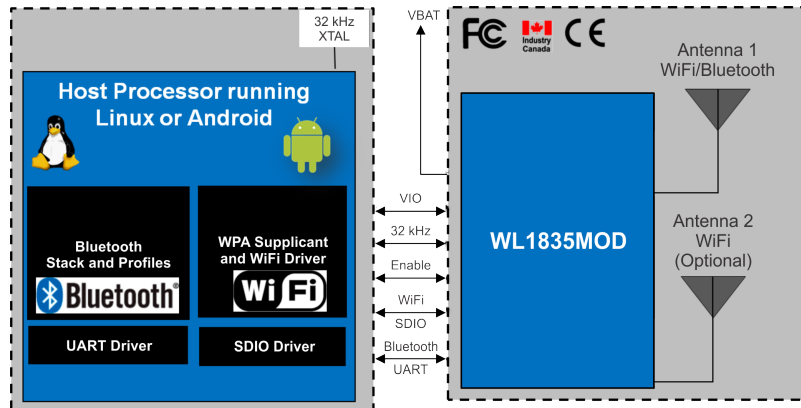


Figure 6-1. WL1835MOD High-Level System Diagram

6.1 WLAN

The device supports the following WLAN features:

- Integrated 2.4-GHz power amplifiers (PAs) for a complete WLAN solution
- Baseband processor: IEEE Std 802.11b/g and IEEE Std 802.11n data rates with 20- or 40-MHz SISO and 20-MHz MIMO
- Fully calibrated system (production calibration not required)
- Medium access controller (MAC)
 - Embedded ARM® central processing unit (CPU)
 - Hardware-based encryption-decryption using 64-, 128-, and 256-bit WEP, TKIP, or AES keys
 - Requirements for Wi-Fi-protected access (WPA and WPA2.0) and IEEE Std 802.11i (includes hardware-accelerated Advanced Encryption Standard [AES])
- New advanced coexistence scheme with *Bluetooth* and BLE
- 2.4-GHz radio
 - Internal LNA and PA
 - IEEE Std 802.11b, 802.11g, and 802.11n
- 4-bit SDIO host interface, including high speed (HS) and V3 modes

6.2 Bluetooth

The device supports the following *Bluetooth* features:

- *Bluetooth* 4.0 as well as CSA2
- Concurrent operation and built-in coexisting and prioritization handling of *Bluetooth*, BLE, audio processing, and WLAN
- Dedicated audio processor supporting on-chip SBC encoding + A2DP
 - Assisted A2DP (A3DP): SBC encoding implemented internally
 - Assisted WB-speech (AWBS): modified SBC codec implemented internally

6.3 BLE

The device supports the following BLE features:

- *Bluetooth* 4.0 BLE dual-mode standard
- All roles and role combinations, mandatory as well as optional
- Up to 10 BLE connections
- Independent LE buffering allowing many multiple connections with no affect on BR-EDR performance

6.4 WiLink 8 Module Markings

Figure 6-2 shows the markings for the TI WiLink 8 module.

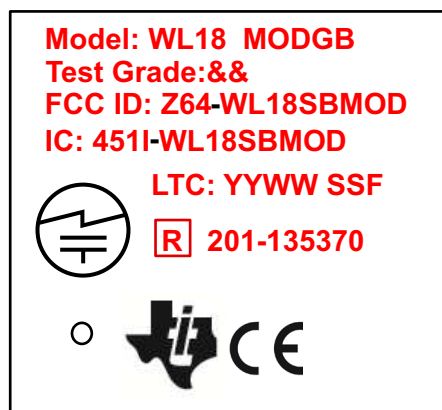


Figure 6-2. WiLink 8 Module Markings

Table 6-4 describes the WiLink 8 module markings.

Table 6-4. Description of WiLink 8 Module Markings

Marking	Description
WL18 MODGB	Model
&&	Test grade (for more information, see Section 6.5, Test Grades)
Z64-WL18SBMOD	FCC ID: single modular FCC grant ID
451I-WL18SBMOD	IC: single modular IC grant ID
YYWWSSF	LTC (lot trace code): • YY = year (for example, 12 = 2012) • WW = week • SS = serial number (01 to 99) matching manufacturer lot number • F = Reserved for internal use
201-135370	R: single modular TELEC grant ID
	TELEC compliance mark
CE	CE compliance mark

6.5 Test Grades

To minimize delivery time, TI may ship the device ordered or an equivalent device currently available that contains at least the functions of the part ordered. From all aspects, this device will behave exactly the same as the part ordered. For example, if a customer orders device WL1801MOD, the part shipped can be marked with a test grade of 37, 07 (see [Table 6-5](#)).

Table 6-5. Test Grade Markings

Mark 1	WLAN	Bluetooth
0&	Tested	–
3&	Tested	Tested
Mark 2	WLAN 2.4 GHz	MIMO 2.4 GHz
&1	Tested	–
&5	Tested	Tested

7 Applications and Implementation

7.1 Application Information

7.1.1 Typical Application – WL1835MOD Reference Design

Figure 7-1 shows the TI WL1835MOD reference design.

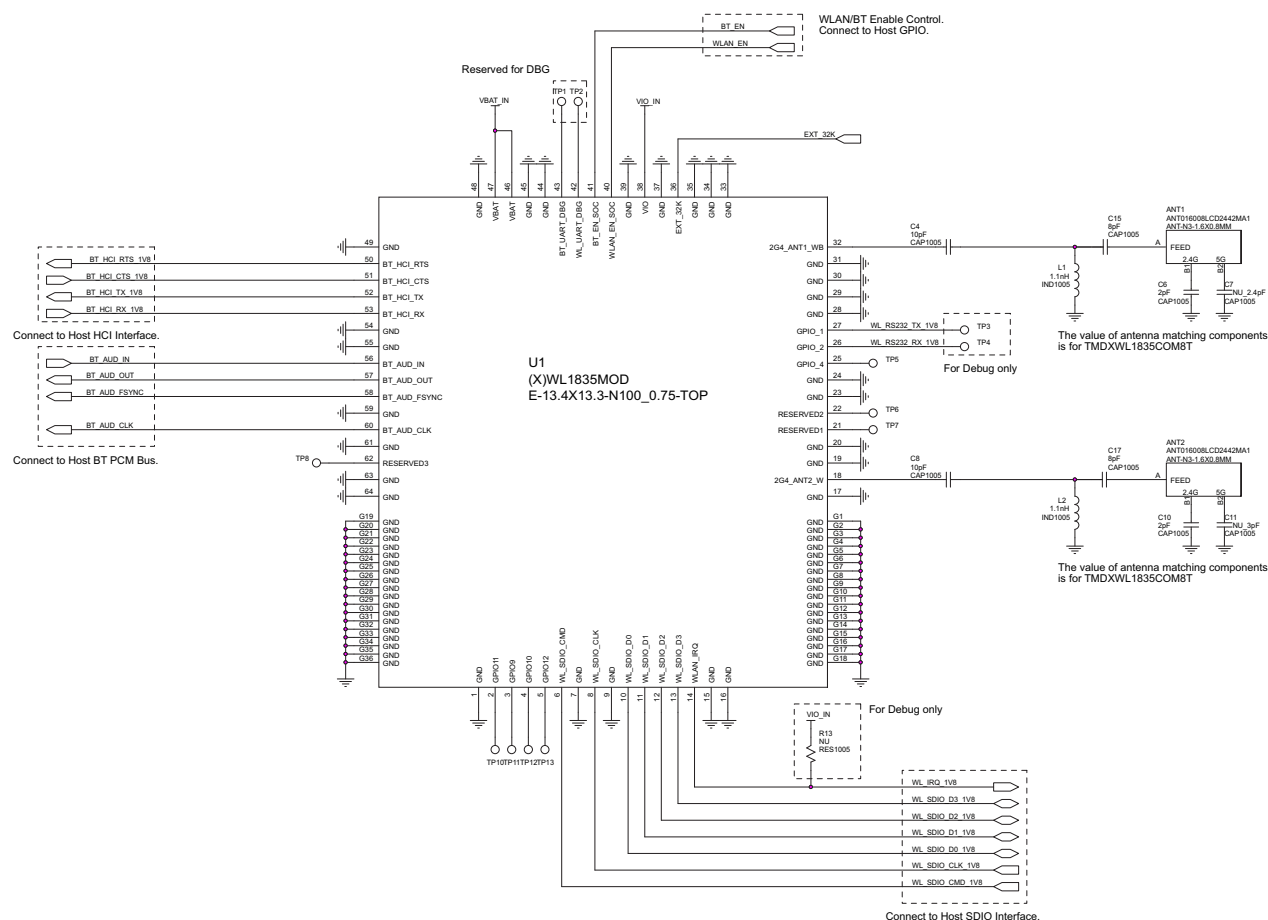


Figure 7-1. TI Module Reference Schematics

Table 7-1 lists the bill materials (BOM).

Table 7-1. Bill of Materials

Description	Part Number	Package	Reference	Qty	Manufacturer
TI WL 1835 WiFi/BT Module	(X)WL1835MOD	13.4 x 13.3 x 2.0mm	U1	1	Texas Instruments
ANT/Chip/2.4, 5 GHz/Peak Gain > 5 dBi	ANT016008LCD2442MA1	1.6 mm x 0.8 mm	ANT1, ANT2	2	TDK
IND 0402/1.2 nH/±0.3/0.12 Ω/300 mA	HI1005-1C1N2SMT	0402	L1, L2	2	ACX
CAP 0402/2.0 pF/50 V/COG/±0.25 pF	C1005C0G1H020C	0402	C8, C10	2	Walsin
CAP 0402/8.2 pF/50 V/NPO/±0.5 pF	0402N8R2D500	0402	C15, C17	2	Walsin
CAP 0402/10 pF/50 V/NPO/±5%	0402N100J500LT	0402	C4, C6	2	Walsin
RES 0402/10K/±5% (debug only)	WR04X103 JTL	0402	R13	1	Walsin

7.1.2 Design Recommendations

This section describes the layout recommendations for the (X)WL1835 module, RF trace, and antenna.

Table 7-2 summarizes the layout recommendations.

Table 7-2. Layout Recommendations Summary

Item	Description
Thermal	
1	The proximity of ground vias must be close to the pad.
2	Signal traces must not be run underneath the module on the layer where the module is mounted.
3	Have a complete ground pour in layer 2 for thermal dissipation.
4	Have a solid ground plane and ground vias under the module for stable system and thermal dissipation.
5	Increase the ground pour in the first layer and have all of the traces from the first layer on the inner layers, if possible.
6	Signal traces can be run on a third layer under the solid ground layer, which is below the module mounting layer.
RF Trace and Antenna Routing	
7	The RF trace antenna feed must be as short as possible beyond the ground reference. At this point, the trace starts to radiate.
8	The RF trace bends must be gradual with an approximate maximum bend of 45 degrees with trace mitered. RF traces must not have sharp corners.
9	RF traces must have via stitching on the ground plane beside the RF trace on both sides.
10	RF traces must have constant impedance (microstrip transmission line).
11	For best results, the RF trace ground layer must be the ground layer immediately below the RF trace. The ground layer must be solid.
12	There must be no traces or ground under the antenna section.
13	RF traces must be as short as possible. The antenna, RF traces, and modules must be on the edge of the PCB product. The proximity of the antenna to the enclosure and the enclosure material must also be considered.
Supply and IF	
14	The power trace for VBAT must be at least 40-mil wide.
15	The 1.8-V trace must be at least 18-mil wide.
16	Make VBAT traces as wide as possible to ensure reduced inductance and trace resistance.
17	If possible, shield VBAT traces with ground above, below, and beside the traces.
18	SDIO signals traces (CLK, CMD, D0, D1, D2, and D3) must be routed in parallel to each other and as short as possible (less than 12 cm). In addition, every trace length must be the same as the others. There should be enough space between traces – greater than 1.5 times the trace width or ground – to ensure signal quality, especially for the SDIO_CLK trace. Remember to keep these traces away from the other digital or analog signal traces. TI recommends adding ground shielding around these buses.
19	SDIO and digital clock signals are a source of noise. Keep the traces of these signals as short as possible. If possible, maintain a clearance around them.

7.1.3 RF Trace and Antenna Layout Recommendations

Figure 7-2 shows the location of the antenna on the WL1835MODCOM8 board as well as the RF trace routing from the (X)WL1835 module (TI reference design). The TDK chip multilayer antennas are mounted on the board with a specific layout and matching circuit for the radiation test conducted in FCC, CE, and IC certifications.

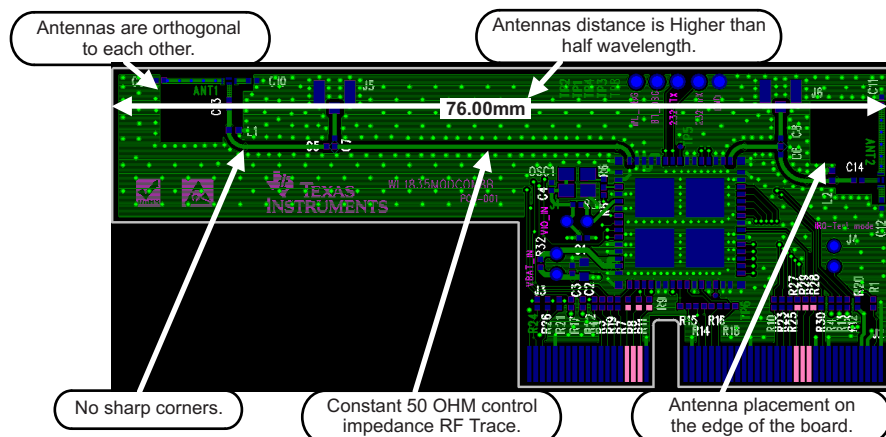


Figure 7-2. Location of Antenna and RF Trace Routing on the TMDXWL1835MODCOM8T Board

Follow these RF trace routing recommendations:

- RF traces must have 50-Ω impedance.
- RF traces must not have sharp corners.
- RF traces must have via stitching on the ground plane beside the RF trace on both sides.
- RF traces must be as short as possible. The antenna, RF traces, and module must be on the edge of the PCB product in consideration of the product enclosure material and proximity.

7.1.4 Module Layout Recommendations

Figure 7-3 shows layer 1 and layer 2 of the TI module layout:

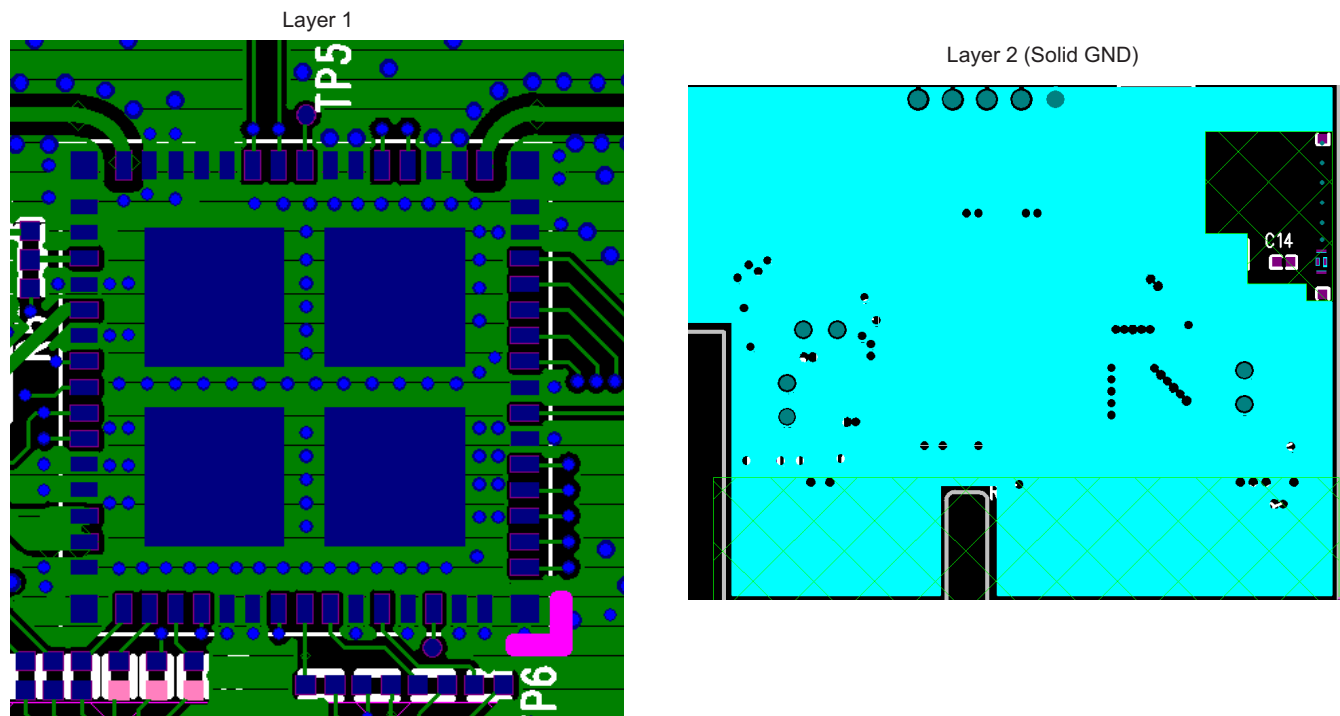


Figure 7-3. TI Module Layout

Follow these module layout recommendations:

- Ensure a solid ground plane and ground vias under the module for stable system and thermal dissipation.

- Do not run signal traces underneath the module on a layer where the module is mounted.
- Signal traces can be run on a third layer under the solid ground layer and beneath the module mounting.
- Run the host interfaces with ground on the adjacent layer to improve the return path.
- TI recommends routing the signals as short as possible to the host.

7.1.5 Thermal Board Recommendations

The TI module uses μ vias for layers 1 through 6 with full copper filling, providing heat flow all the way to the module ground pads.

TI recommends using one big ground pad under the module with vias all the way to connect the pad to all ground layers (see [Figure 7-4](#)).

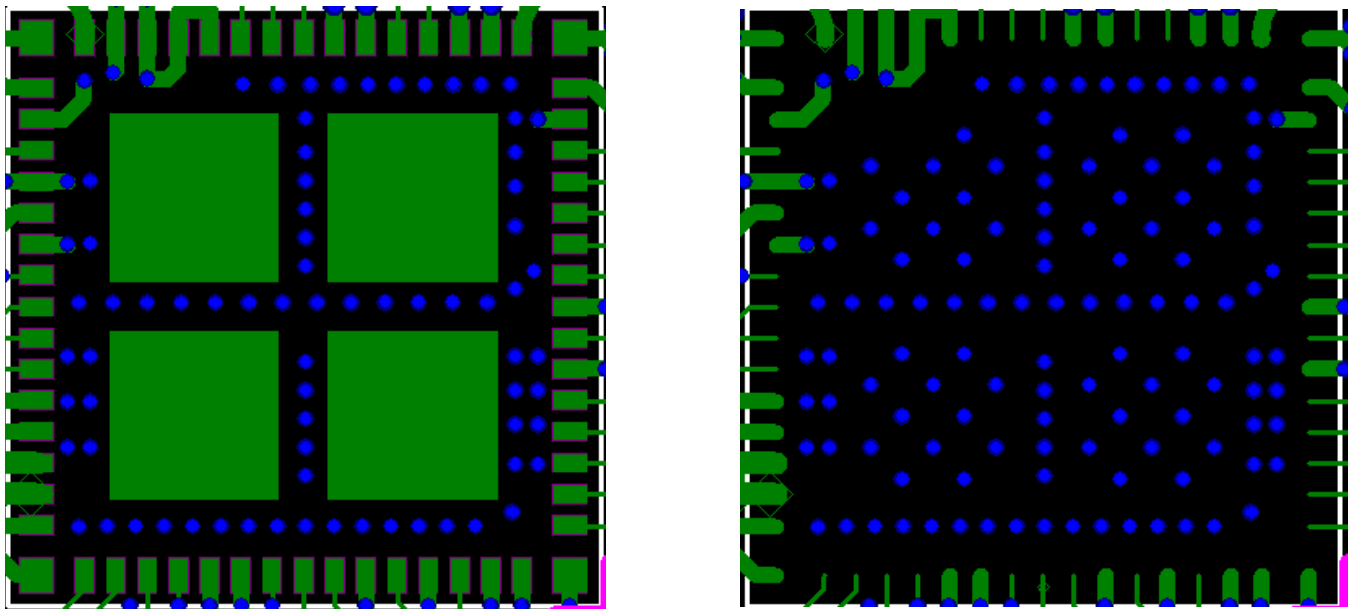
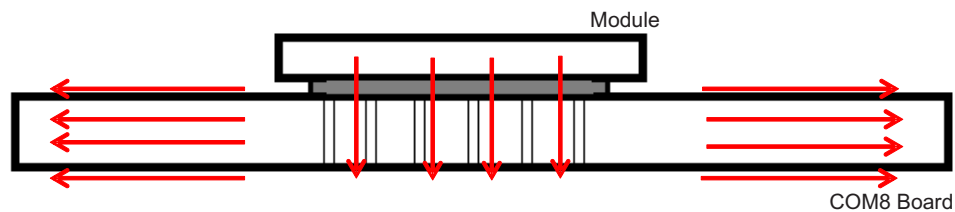


Figure 7-4. Block of Ground Pads on Bottom Side of Package

[Figure 7-5](#) shows via array patterns, which are applied wherever possible to connect all of the layers to the TI module central or main ground pads.



Figure 7-5. Via Array Patterns

7.1.6 Baking and SMT Recommendations

7.1.6.1 Baking Recommendations

Follow these baking guidelines for the WiLink 8 module:

- Follow MSL level 3 to perform the baking process.
- After the bag is open, devices subjected to reflow solder or other high temperature processes must be mounted within 168 hours of factory conditions (< 30°C/60% RH) or stored at <10% RH.
- if the Humidity Indicator Card reads >10%, devices require baking before being mounted.
- If baking is required, bake devices for 8 hours at 125 °C.

7.1.6.2 SMT Recommendations

Figure 7-6 shows the recommended reflow profile for the WiLink 8 module.

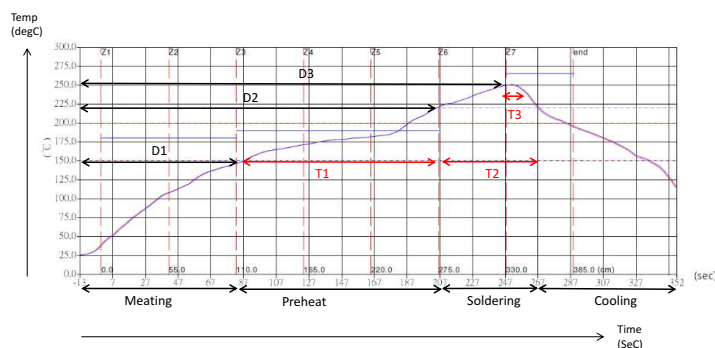


Figure 7-6. Reflow Profile for the WiLink 8 Module

Table 7-3 lists the temperature values for the profile shown in Figure 7-6.

Table 7-3. Temperature Values for Reflow Profile

Item	Temperature (°C)	Time (s)
Preheat	D1 to approximately D2: 140 to 200	T1: 80 to approximately 120
Soldering	D2: 220	T2: 60 ±10
Peak temperature	D3: 250 max	T3: 10

8 Device and Documentation Support

8.1 Device Support

8.1.1 Development Support

For a complete listing of development-support tools, visit the Texas Instruments [WL18xx Wiki](#). For information on pricing and availability, contact the nearest TI field sales office or authorized distributor.

8.1.2 Device Support Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers. These prefixes represent evolutionary stages of product development from engineering prototypes through fully qualified production devices.

- X Experimental, preproduction, sample or prototype device. Device may not meet all product qualification conditions and may not fully comply with TI specifications. Experimental/Prototype devices are shipped against the following disclaimer: "This product is still in development and is intended for internal evaluation purposes." Notwithstanding any provision to the contrary, TI makes no warranty expressed, implied, or statutory, including any implied warranty of merchantability of fitness for a specific purpose, of this device.
- null Device is qualified and released to production. TI's standard warranty applies to production devices.

8.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 8-1. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
WL1801MOD	Click here	Click here	Click here	Click here	Click here
WL1805MOD	Click here	Click here	Click here	Click here	Click here
WL1831MOD	Click here	Click here	Click here	Click here	Click here
WL1835MOD	Click here	Click here	Click here	Click here	Click here

8.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

[TI E2E™ Online Community](#) *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

[TI Embedded Processors Wiki](#) *Texas Instruments Embedded Processors Wiki*. Established to help developers get started with Embedded Processors from Texas Instruments and to foster innovation and growth of general knowledge about the hardware and software surrounding these devices.

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8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

9 Mechanical Packaging and Orderable Information

Figure 9-1 shows the mechanical outline for the device.

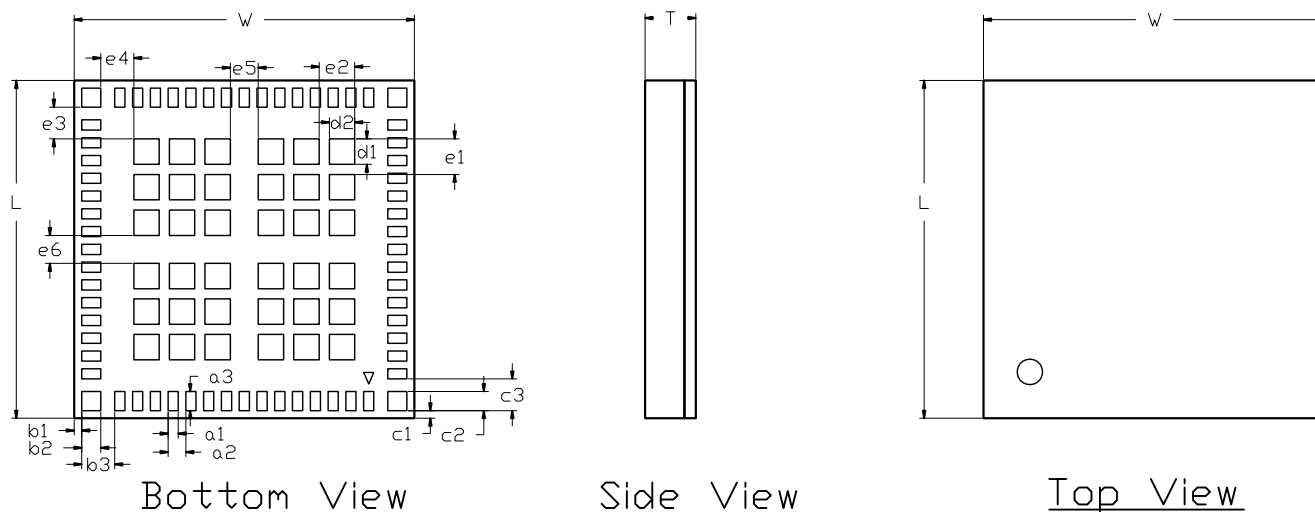


Figure 9-1. TI Module Mechanical Outline

Table 9-1 lists the dimensions for the mechanical outline of the device.

Table 9-1. Dimensions for TI Module Mechanical Outline

Marking	Min (mm)	Nom (mm)	Max (mm)	Marking	Min (mm)	Nom (mm)	Max (mm)
L (body size)	13.20	13.30	13.40	c2	0.65	0.75	0.85
W (body size)	13.30	13.40	13.50	c3	1.15	1.25	1.35
T (thickness)	1.90		2.00	d1	0.90	1.00	1.10
a1	0.30	0.40	0.50	d2	0.90	1.00	1.10
a2	0.60	0.70	0.80	e1	1.30	1.40	1.50
a3	0.65	0.75	0.85	e2	1.30	1.40	1.50
b1	0.20	0.30	0.40	e3	1.15	1.25	1.35
b2	0.65	0.75	0.85	e4	1.20	1.30	1.40
b3	1.20	1.30	1.40	e5	1.00	1.10	1.20
c1	0.20	0.30	0.40	e6	1.00	1.10	1.20

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
WL1801MODGBMOCR	ACTIVE			100	1200	TBD	Call TI	Call TI	-20 to 70		Samples
WL1801MODGBMOCT	ACTIVE			100	250	TBD	Call TI	Call TI	-20 to 70		Samples
WL1805MODGBMOCR	ACTIVE			100	1200	TBD	Call TI	Call TI	-20 to 70		Samples
WL1805MODGBMOCT	ACTIVE			100	250	TBD	Call TI	Call TI	-20 to 70		Samples
WL1831MODGBMOCR	ACTIVE			100	1200	TBD	Call TI	Call TI	-20 to 70		Samples
WL1831MODGBMOCT	ACTIVE			100	250	TBD	Call TI	Call TI	-20 to 70		Samples
WL1835MODGBMOCR	ACTIVE			100	1200	TBD	Call TI	Call TI	-20 to 70		Samples
WL1835MODGBMOCT	ACTIVE			100	250	TBD	Call TI	Call TI	-20 to 70		Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

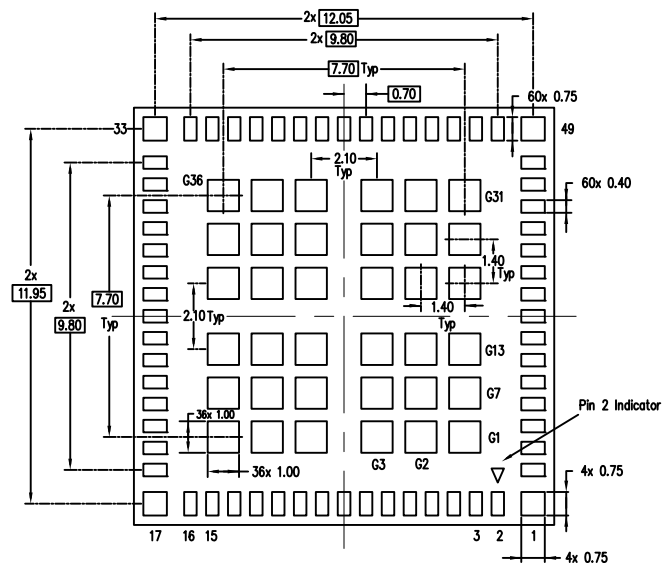
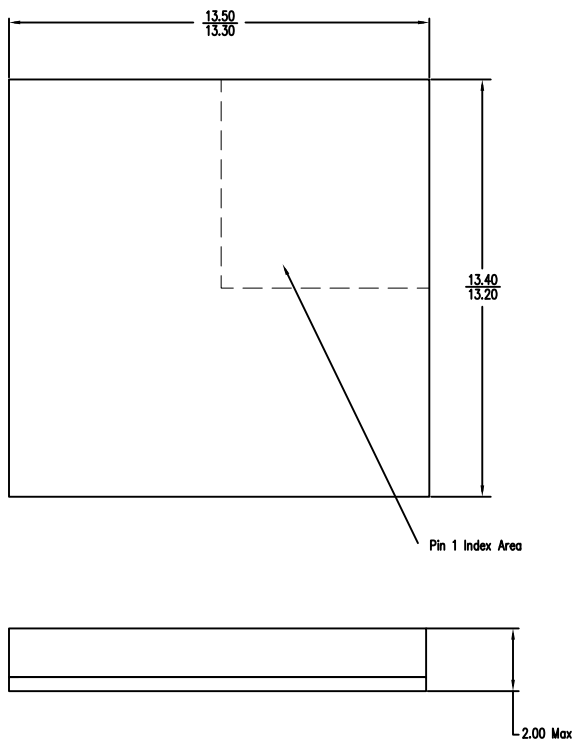
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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NOTES:

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